

**10A, 500V, 0.500 Ohm, N-Channel Power MOSFET**

This is an N-Channel enhancement mode silicon gate power field effect transistor designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high power bipolar switching transistors requiring high speed and low gate drive power. This type can be operated directly from integrated circuits.

Formerly developmental type TA17435.

**Ordering Information**

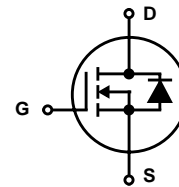
PART NUMBER	PACKAGE	BRAND
BUZ45B	TO-204AA	BUZ45B

NOTE: When ordering, use the entire part number.

**Features**

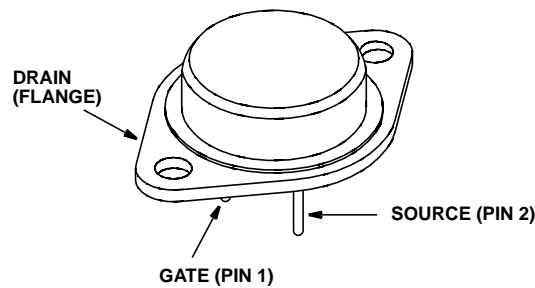
- 10A, 500V
- $r_{DS(ON)} = 0.500\Omega$
- SOA is Power Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance
- Majority Carrier Device

**Symbol**



**Packaging**

JEDEC TO-204AA



# BUZ45B

## Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

	BUZ45B	UNITS
Drain to Source Breakdown Voltage (Note 1) . . . . .	500	V
Drain to Gate Voltage ( $R_{GS} = 20k\Omega$ ) (Note 1) . . . . .	500	V
Continuous Drain Current ( $T_C = 35^\circ\text{C}$ ) . . . . .	10	A
Pulsed Drain Current (Note 3) . . . . .	40	A
Gate to Source Voltage . . . . .	$\pm 20$	V
Maximum Power Dissipation . . . . .	125	W
Linear Derating Factor . . . . .	1.0	$W/^\circ\text{C}$
Operating and Storage Temperature . . . . .	-55 to 150	$^\circ\text{C}$
DIN Humidity Category - DIN 40040 . . . . .	E	
IEC Climatic Category - DIN IEC 68-1 . . . . .	55/150/56	
Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10s . . . . .	260	$^\circ\text{C}$

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

**NOTE:**

1.  $T_J = 25^\circ\text{C}$  to  $125^\circ\text{C}$ .

## Electrical Specifications $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	$BV_{DSS}$	$I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$	500	-	-	V
Gate to Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$ , $I_D = 1\text{mA}$ (Figure 9)	2.1	3	4	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$T_J = 25^\circ\text{C}$ , $V_{DS} = 500\text{V}$ , $V_{GS} = 0\text{V}$	-	20	250	$\mu\text{A}$
		$T_J = 125^\circ\text{C}$ , $V_{DS} = 500\text{V}$ , $V_{GS} = 0\text{V}$	-	100	1000	$\mu\text{A}$
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS} = 20\text{V}$ , $V_{DS} = 0\text{V}$	-	10	100	nA
Drain to Source On Resistance (Note 2)	$r_{DS(ON)}$	$I_D = 5\text{A}$ , $V_{GS} = 10\text{V}$ (Figure 8)	-	0.49	0.50	$\Omega$
Forward Transconductance (Note 2)	$g_{fs}$	$V_{DS} = 25\text{V}$ , $I_D = 5\text{A}$ (Figure 11)	2.7	5	-	S
Turn-On Delay Time	$t_{d(ON)}$	$V_{CC} = 30\text{V}$ , $I_D \approx 2.9\text{A}$ , $V_{GS} = 10\text{V}$ , $R_{GS} = 50\Omega$ , $R_L = 10\Omega$ . (Figures 14, 15)	-	50	75	ns
Rise Time	$t_r$		-	80	120	ns
Turn-Off Delay Time	$t_{d(OFF)}$		-	330	430	ns
Fall Time	$t_f$		-	110	140	ns
Input Capacitance	$C_{ISS}$	$V_{DS} = 25\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$ (Figure 10)	-	3800	4900	pF
Output Capacitance	$C_{OSS}$		-	250	400	pF
Reverse Transfer Capacitance	$C_{RSS}$		-	100	170	pF
Thermal Resistance Junction to Case	$R_{\theta JC}$		$\leq 1$			$^\circ\text{C/W}$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$		$\leq 35$			$^\circ\text{C/W}$

## Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Continuous Source to Drain Current	$I_{SD}$	$T_C = 25^\circ\text{C}$	-	-	10	A
Pulsed Source to Drain Current	$I_{SDM}$		-	-	40	A
Source to Drain Diode Voltage	$V_{SD}$	$T_J = 25^\circ\text{C}$ , $I_{SD} = 20\text{A}$ , $V_{GS} = 0\text{V}$	-	1.3	1.7	V
Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ\text{C}$ , $I_{SD} = 10\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$ , $V_R = 100\text{V}$	-	1200	-	ns
Reverse Recovery Charge	$Q_{RR}$		-	12	-	$\mu\text{C}$

**NOTES:**

2. Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Repetitive rating: pulse width limited by maximum junction temperature. See Transient Thermal Impedance curve (Figure 3).

Typical Performance Curves Unless Otherwise Specified

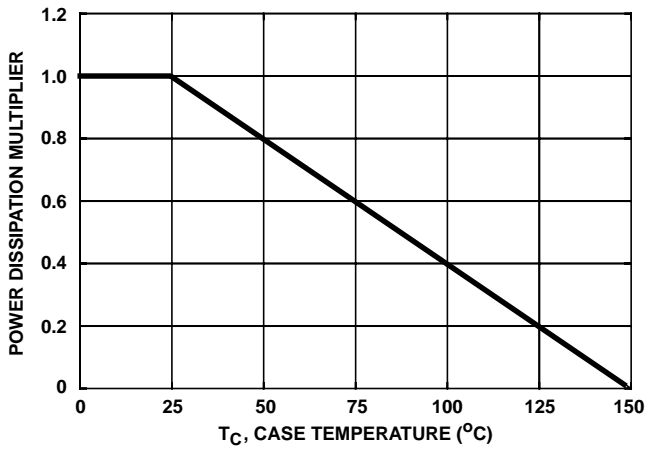


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

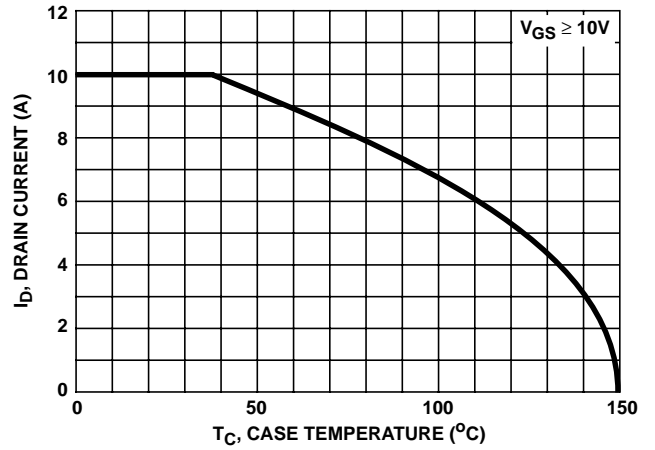


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

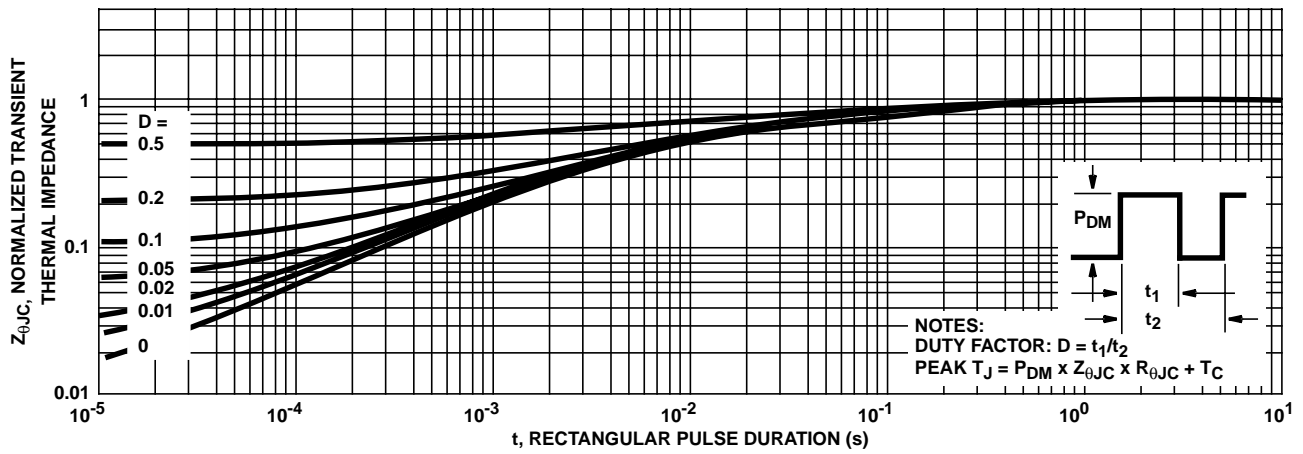


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

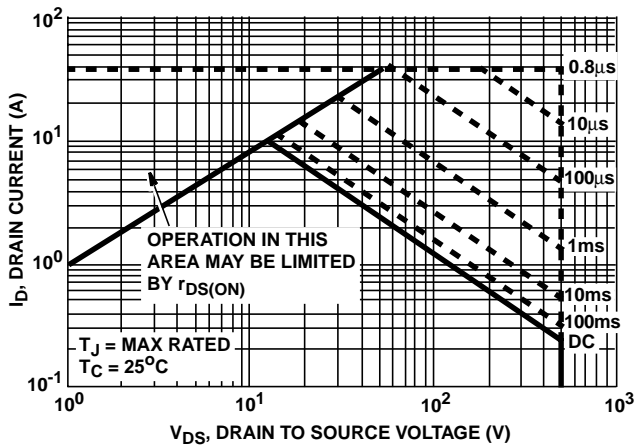


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

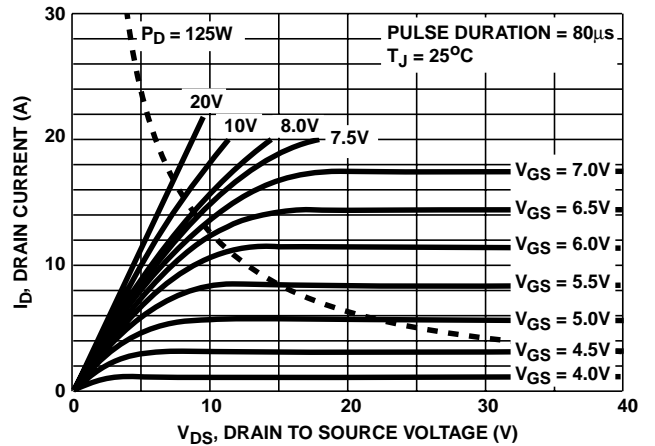


FIGURE 5. OUTPUT CHARACTERISTICS

Typical Performance Curves Unless Otherwise Specified (Continued)

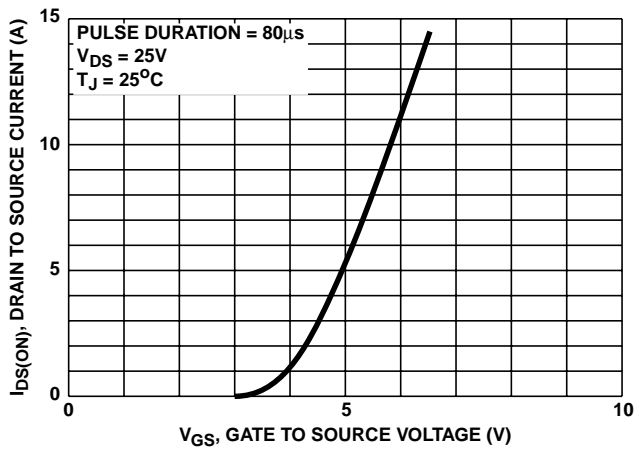


FIGURE 6. TRANSFER CHARACTERISTICS

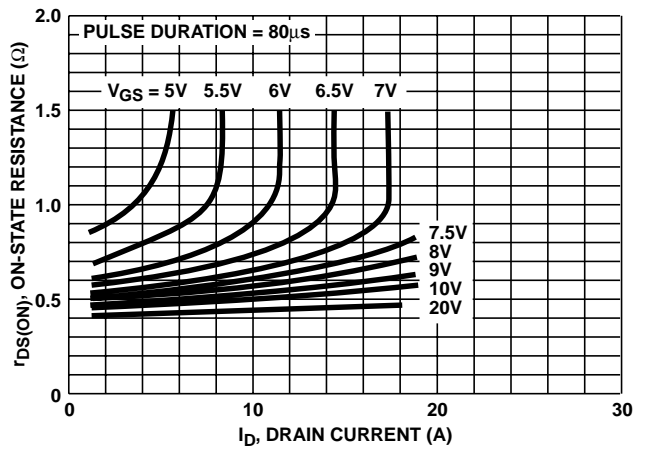


FIGURE 7. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

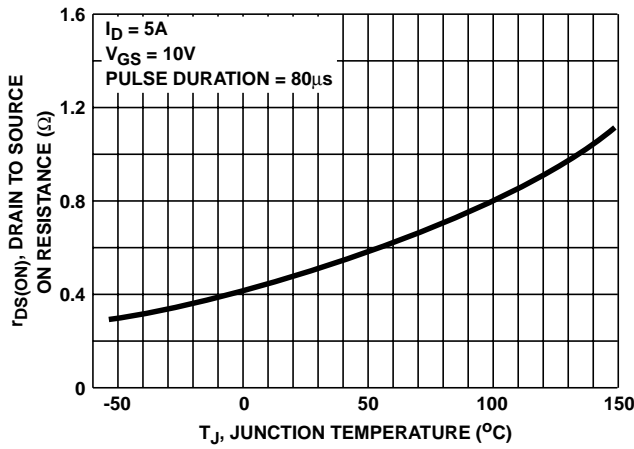


FIGURE 8. DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

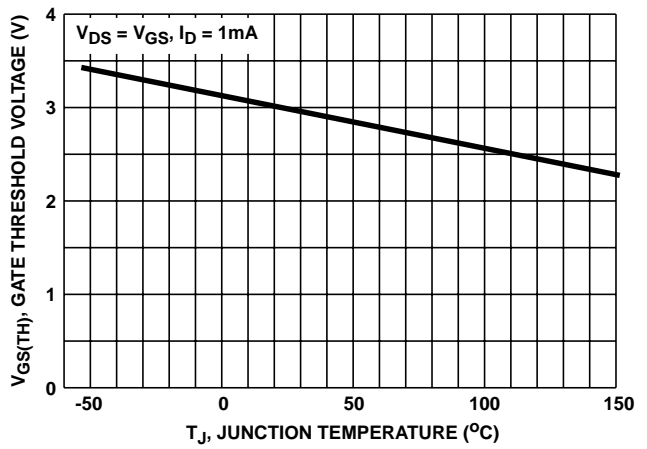


FIGURE 9. GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

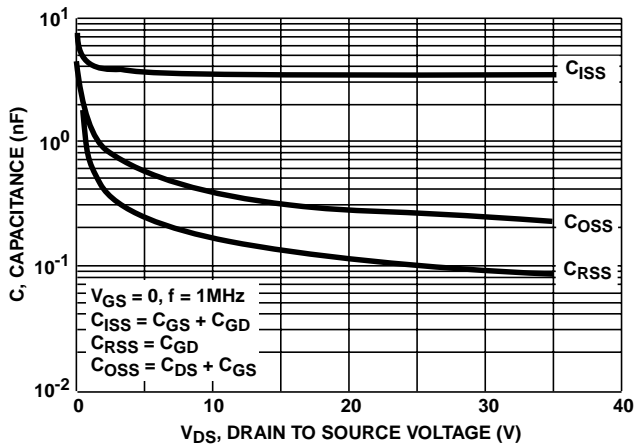


FIGURE 10. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

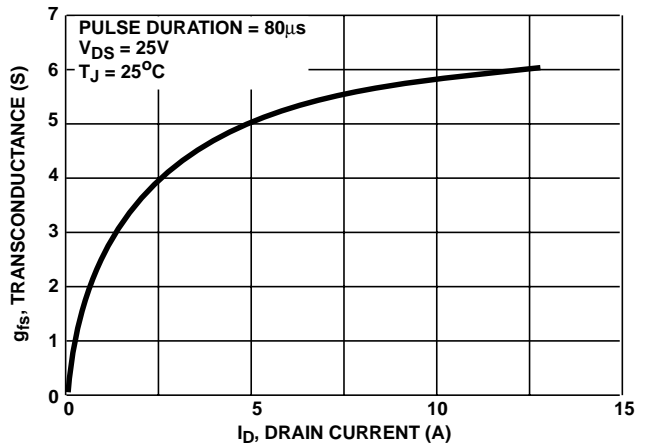


FIGURE 11. TRANSCONDUCTANCE vs DRAIN CURRENT

Typical Performance Curves Unless Otherwise Specified (Continued)

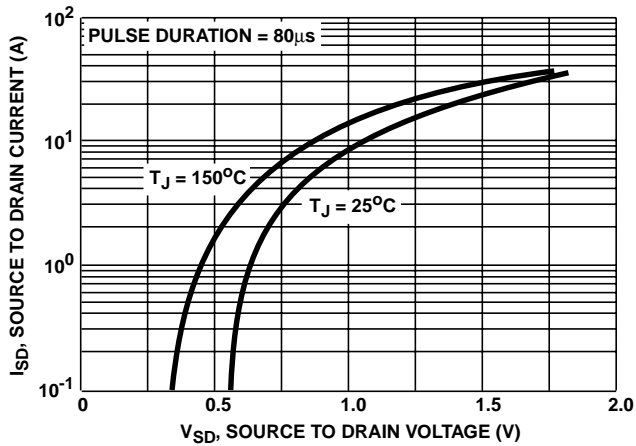


FIGURE 12. SOURCE TO DRAIN DIODE VOLTAGE

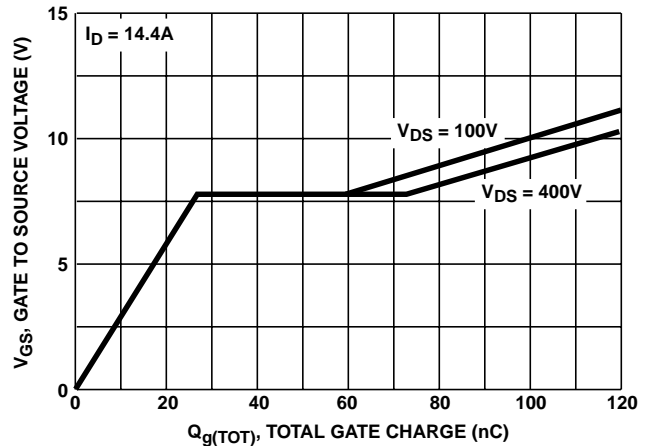


FIGURE 13. GATE TO SOURCE VOLTAGE vs GATE CHARGE

Test Circuits and Waveforms

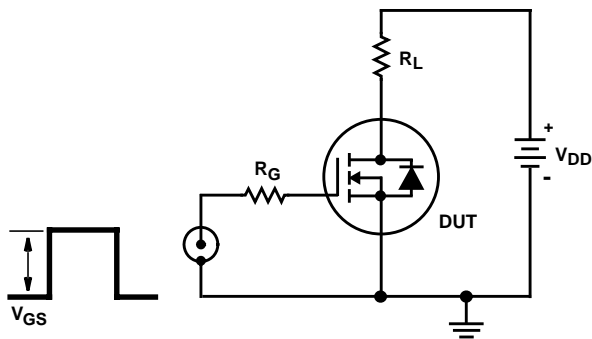


FIGURE 14. SWITCHING TIME TEST CIRCUIT

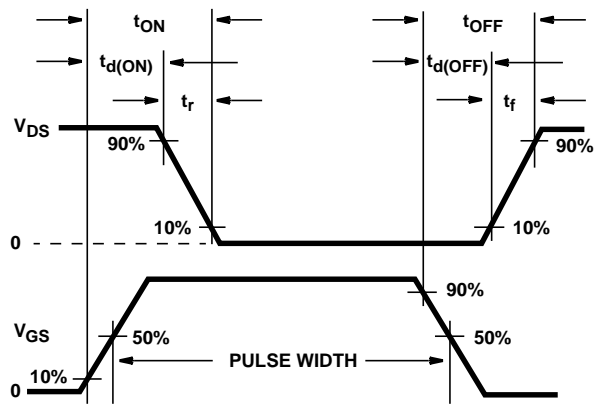


FIGURE 15. RESISTIVE SWITCHING WAVEFORMS

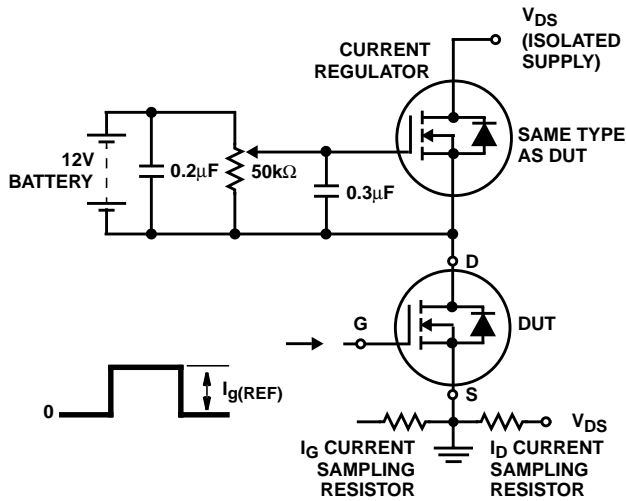


FIGURE 16. GATE CHARGE TEST CIRCUIT

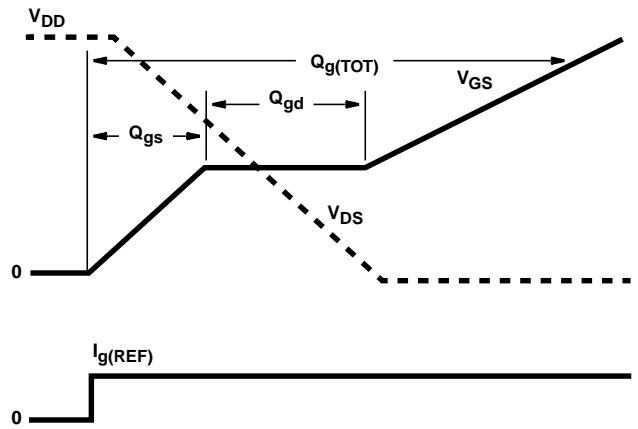


FIGURE 17. GATE CHARGE WAVEFORMS